



Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}			32	C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	80	C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	C

Electrical Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	80			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.5		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 0.8 BV_{DSS},$ $V_{GS} = 0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	



Fig.1 Gate-Charge Characteristics

Fig.2 Capacitance Characteristics

Fig.3 Power Dissipation

Fig.4 Typical output Characteristics

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Fig.5 Threshold Voltage V.S Junction Temperature

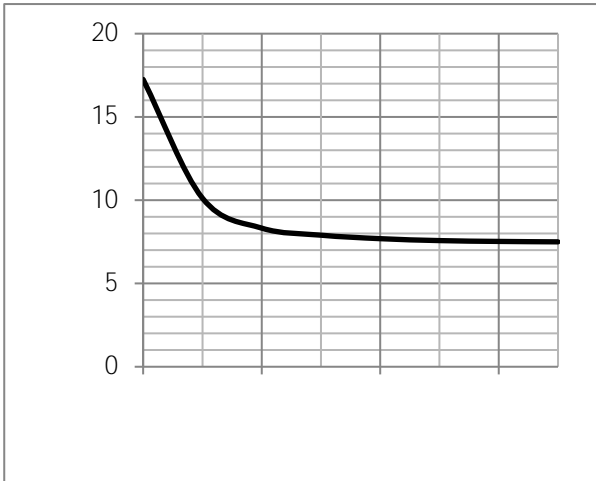


Fig.9 SOA Maximum Safe Operating Area

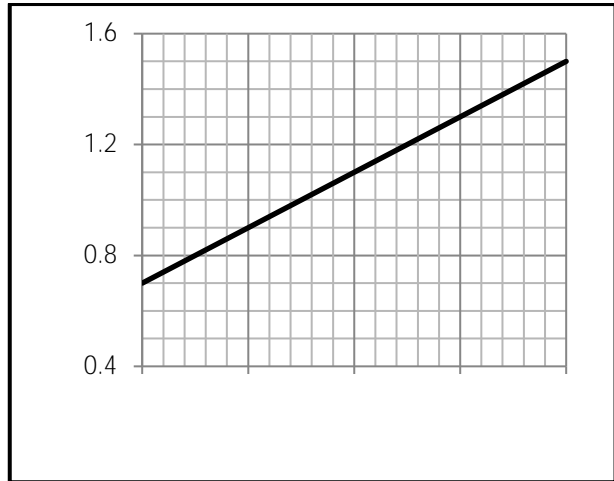


Fig.10 I_D -Junction Temperature

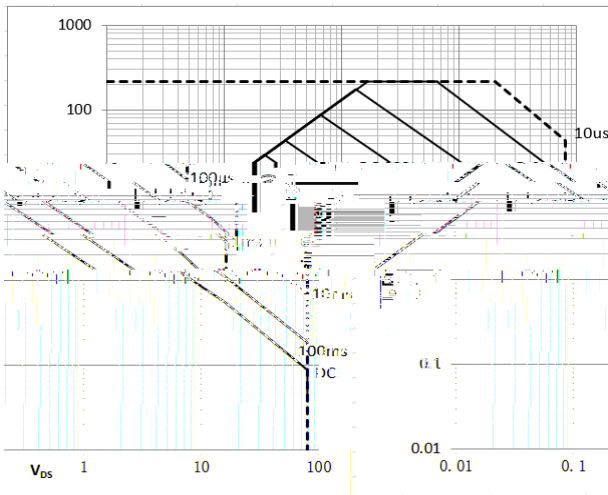


Fig.11 Switching Time Measurement Circuit

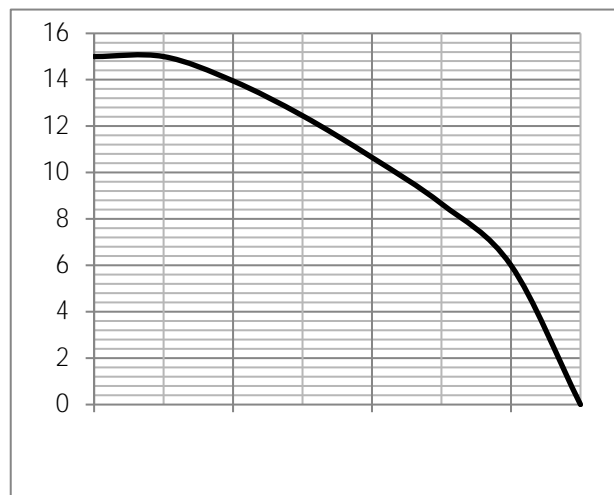


Fig.12 Gate Charge Waveform

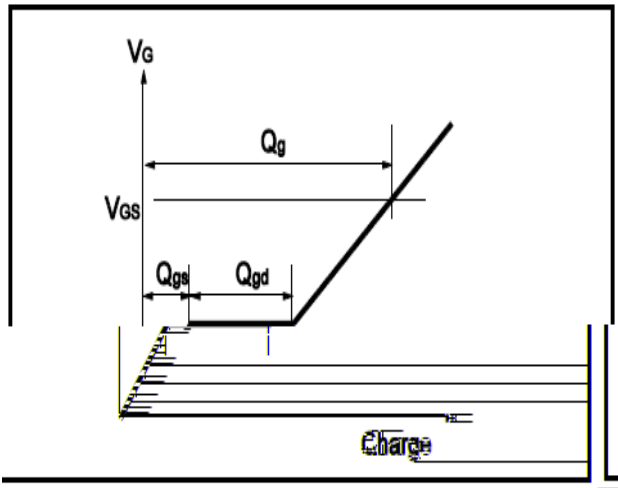
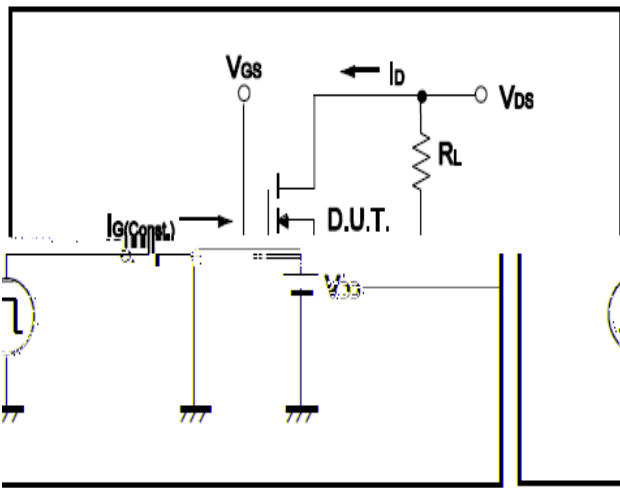


Fig.13 Switching Time Measurement Circuit

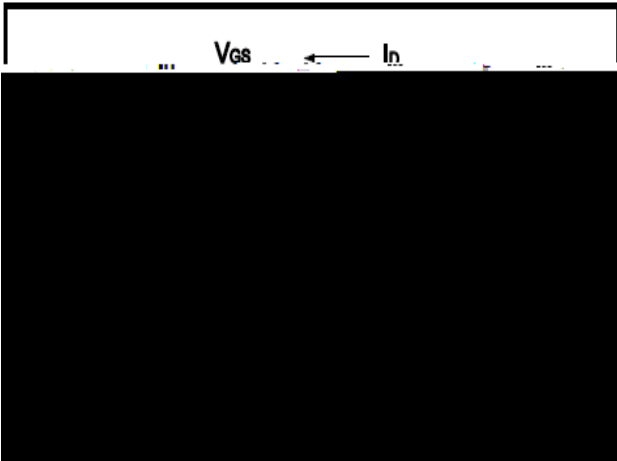
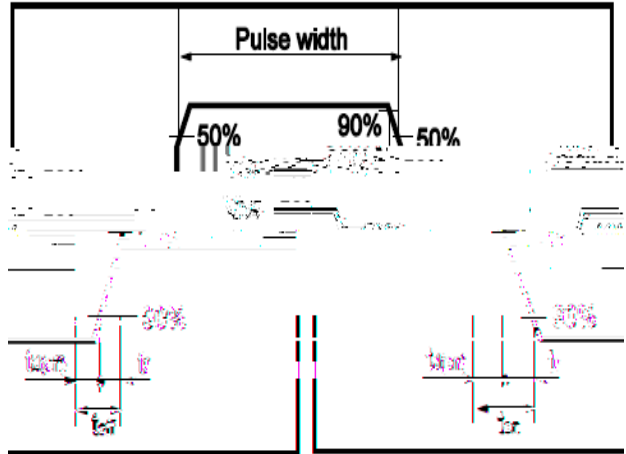


Fig.14 Gate Charge Waveform





(SOP8)

Unit: mm

